

Product Summary

$V_{(BR)DSS}$	$R_{DS(on)TYP}$	I_D
30V	5.5mΩ@10V	50A
	7.7mΩ@4.5V	

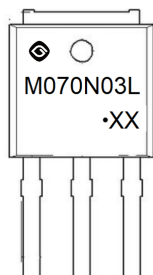
Feature

- Trench Technology Power MOSFET
- Low $R_{DS(on)}$
- Low Gate Charge
- Low Gate Resistance
- 100% UIS Tested

Application

- Power Switching Application

MARKING:

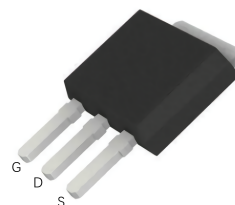


M070N03L = Device Code

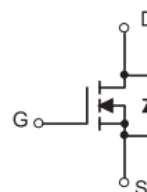
XX = Date Code

Solid Dot = Green Indicator

TO-251-3L



Schematic diagram



ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$ unless otherwise noted)

Parameter		Symbol	Value	Unit
Drain - Source Voltage		V_{DS}	30	V
Gate - Source Voltage		V_{GS}	± 20	V
Continuous Drain Current ¹	$T_C = 25^\circ\text{C}$	I_D	50	A
Continuous Drain Current ¹	$T_C = 100^\circ\text{C}$	I_D	40	A
Continuous Drain Current ⁶	$T_A = 25^\circ\text{C}$	I_D	15	A
Pulsed Drain Current ²		I_{DM}	130	A
Single Pulsed Avalanche Current ³		I_{AS}	20	A
Single Pulsed Avalanche Energy ³		E_{AS}	100	mJ
Power Dissipation ⁵	$T_C = 25^\circ\text{C}$	P_D	35	W
Power Dissipation ⁶	$T_A = 25^\circ\text{C}$	P_D	3.5	W
Thermal Resistance from Junction to Ambient ⁶		$R_{\theta JA}$	35	$^\circ\text{C/W}$
Thermal Resistance from Junction to Case		$R_{\theta JC}$	5	$^\circ\text{C/W}$
Junction Temperature		T_J	150	$^\circ\text{C}$
Storage Temperature		T_{STG}	-55~ +150	$^\circ\text{C}$

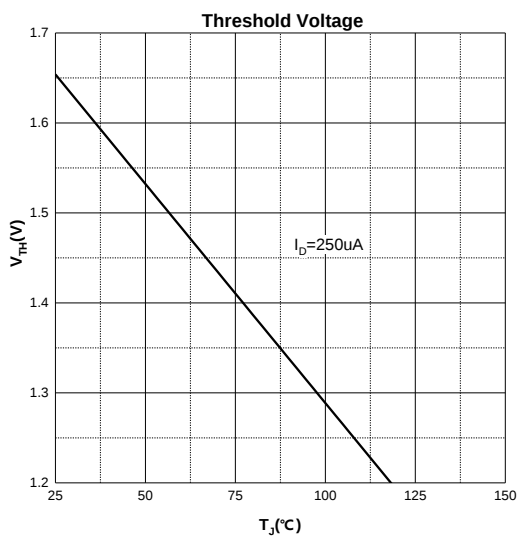
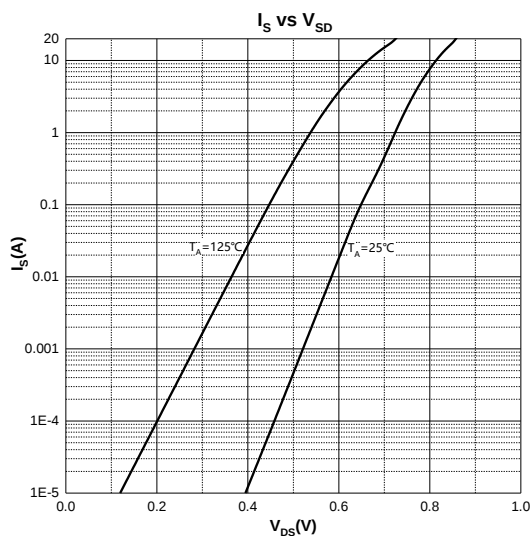
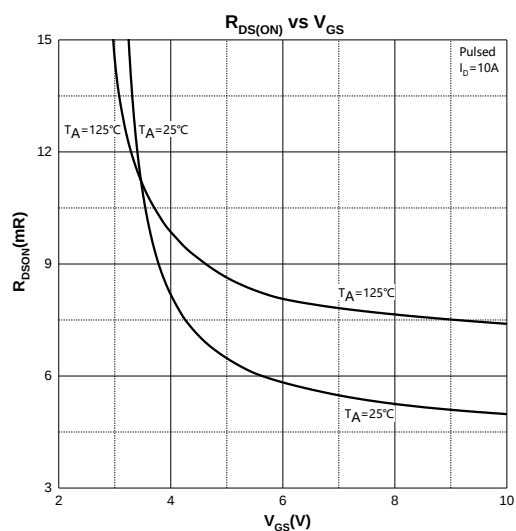
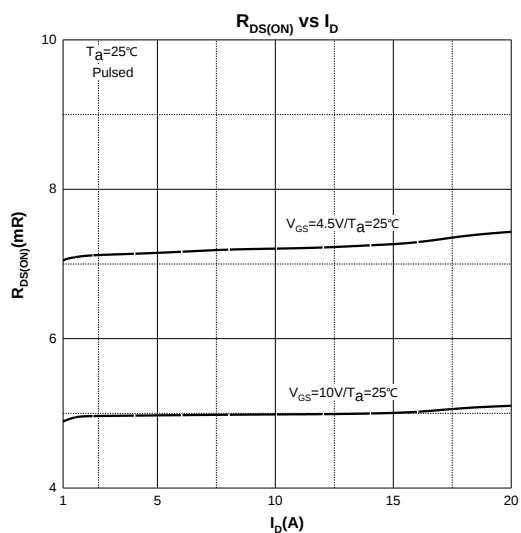
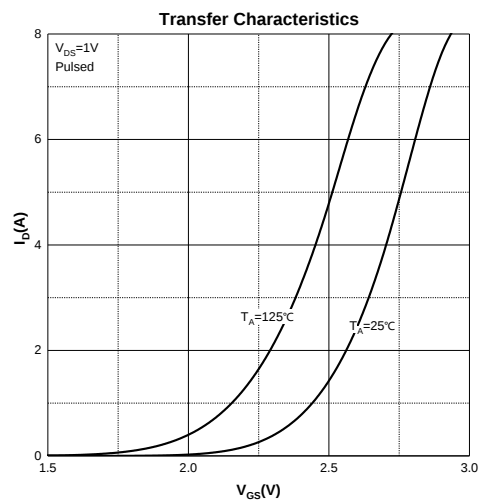
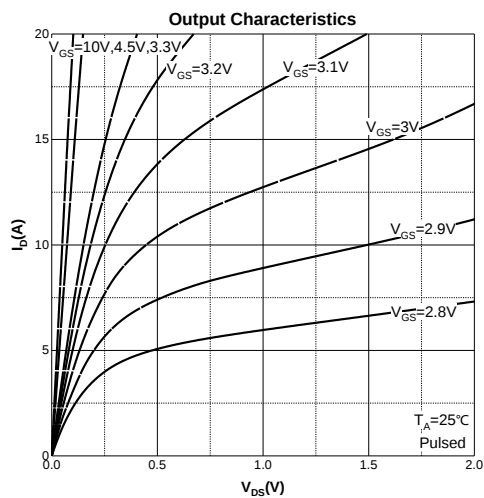
MOSFET ELECTRICAL CHARACTERISTICS (T_J = 25°C unless otherwise noted)

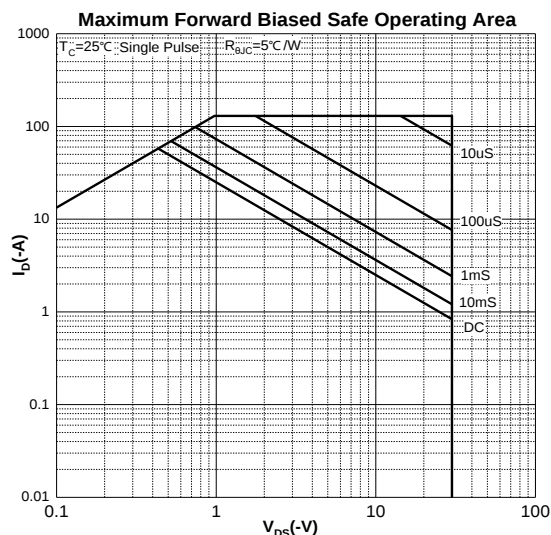
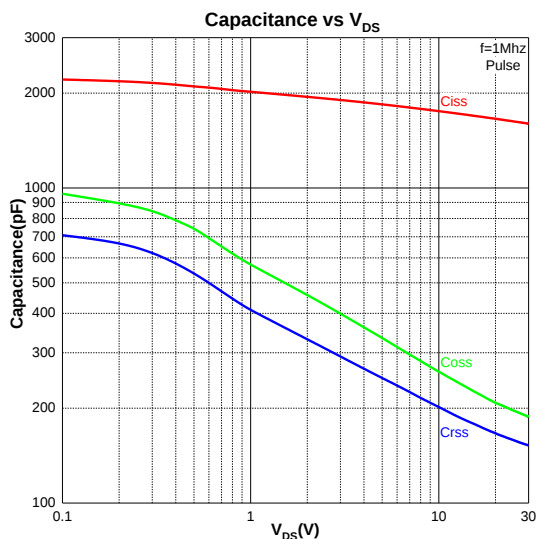
Parameter	Symbol	Test Condition	Min	Type	Max	Unit
Off Characteristics						
Drain - Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} = 0V, I _D = 250μA	30			V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 24V, V _{GS} = 0V			1	μA
Gate - Body Leakage Current	I _{GSS}	V _{GS} = ±20V, V _{DS} = 0V			±100	nA
On Characteristics ⁴						
Gate Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250μA	1.0	1.6	3.0	V
Drain-source On-resistance	R _{DS(on)}	V _{GS} = 10V, I _D = 10A		5.5	7.0	mΩ
		V _{GS} = 4.5V, I _D = 10A		7.5	11.5	
Dynamic Characteristics						
Input Capacitance	C _{iss}	V _{DS} = 15V, V _{GS} = 0V, f = 1MHz		1666		pF
Output Capacitance	C _{oss}			222		
Reverse Transfer Capacitance	C _{rss}			176		
Gate Resistance	R _g	V _{DS} = 0V, V _{GS} = 0V, f = 1MHz		1.48		Ω
Switching Characteristics						
Total Gate Charge	Q _g	V _{DS} = 15V, V _{GS} = 4.5V, I _D = 20A		15		nC
Gate-source Charge	Q _{gs}			3.8		
Gate-drain Charge	Q _{gd}			5.5		
Turn-on Delay Time	t _{d(on)}	V _{DD} = 15V, V _{GS} = 10V, R _L = 0.75Ω R _G = 3Ω		6		ns
Turn-on Rise Time	t _r			10		
Turn-off Delay Ttime	t _{d(off)}			16		
Turn-off Fall Time	t _f			4		
Source - Drain Diode Characteristics						
Diode Forward Voltage ⁴	V _{SD}	V _{GS} = 0V, I _S = 10A			1.2	V

Notes :

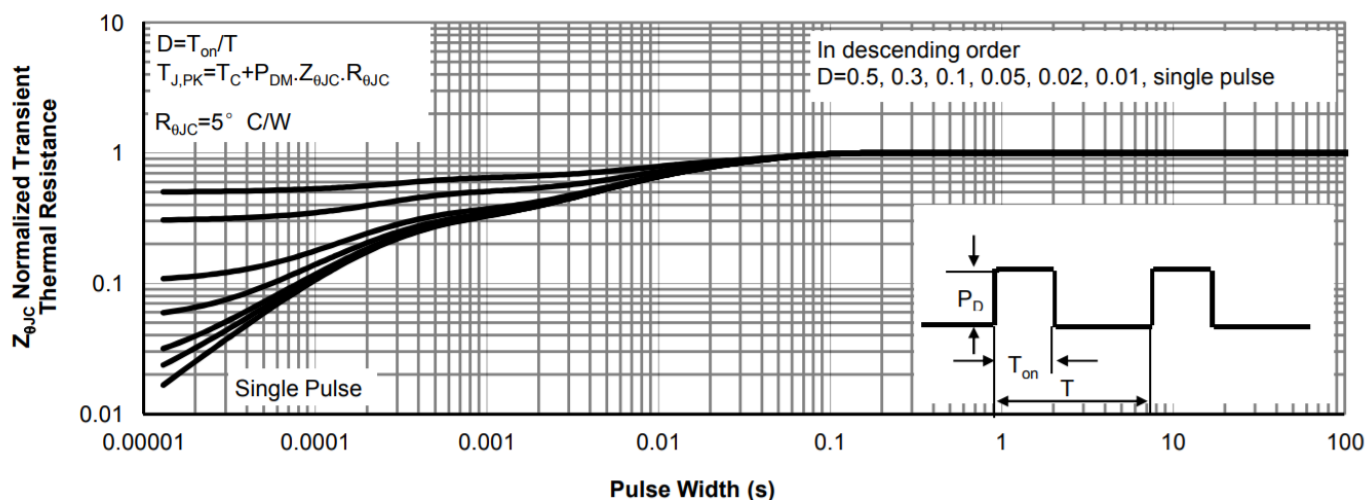
- 1.The maximum current rating is limited by package.And device mounted on a large heatsink
- 2.Pulse Test : Pulse Width ≤ 10μs, duty cycle ≤ 1%.
- 3.EAS condition: V_{DD} = 25V, V_{GS} = 10V, L = 0.5mH, R_G = 25Ω Starting T_J = 25°C.
- 4.Pulse Test : Pulse Width ≤ 300μs, duty cycle ≤ 2%.
- 5.The power dissipation P_D is limited by T_{J(MAX)} = 150°C.And device mounted on a large heatsink
- 6.Device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with T_A = 25°C.

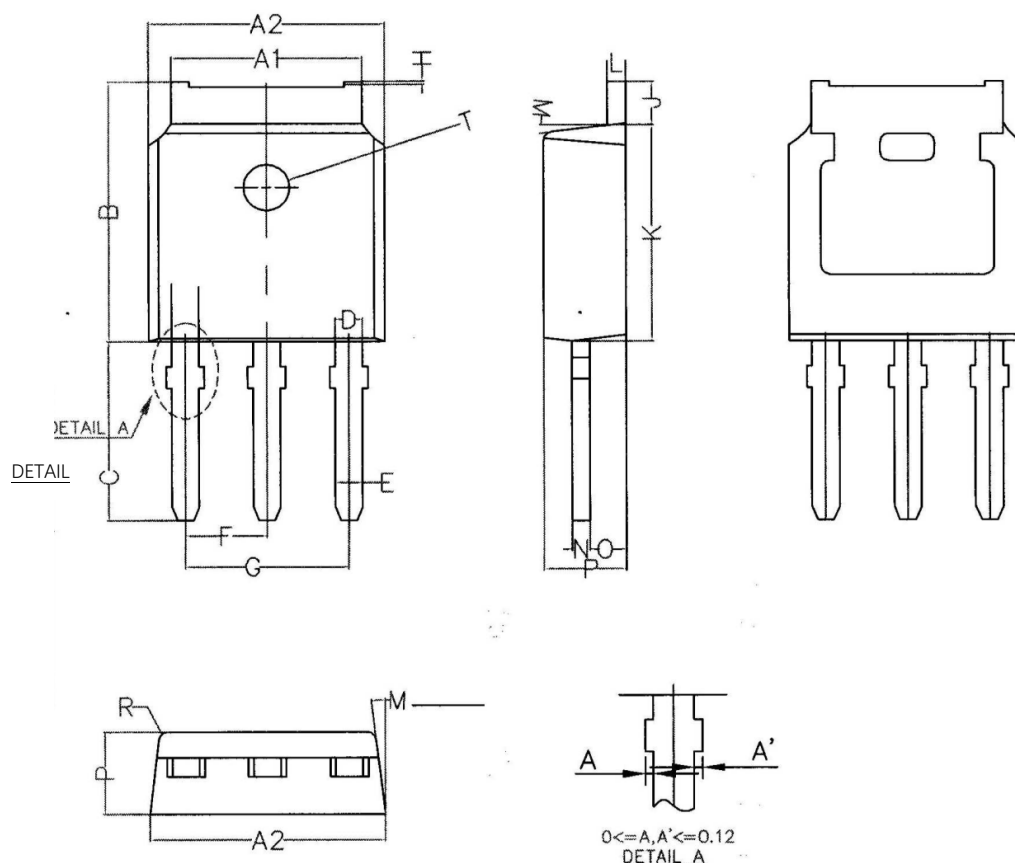
Typical Characteristics





Normalized Maximum Transient Thermal Impedance



TO-251-3L Package Information


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A1	5.220	5.420	0.206	0.213
A2	6.550	6.650	0.258	0.262
B	7.050	7.150	0.278	0.281
C	4.800	5.200	0.189	0.205
D	1.000TYP		0.039TYP	
E	0.760TYP		0.030TYP	
F	2.286TYP		0.090TYP	
G	4.572TYP		0.180TYP	
H	0.150TYP		0.006TYP	
J	0.950	1.050	0.037	0.041
K	6.05	6.15	0.238	0.242
L	0.508TYP		0.020TYP	
M	7°		7°	
N	0.508TYP		0.020TYP	
O	0.960	1.060	0.038	0.042
P	2.250	2.350	0.089	0.093
R	0.25		0.010TYP	